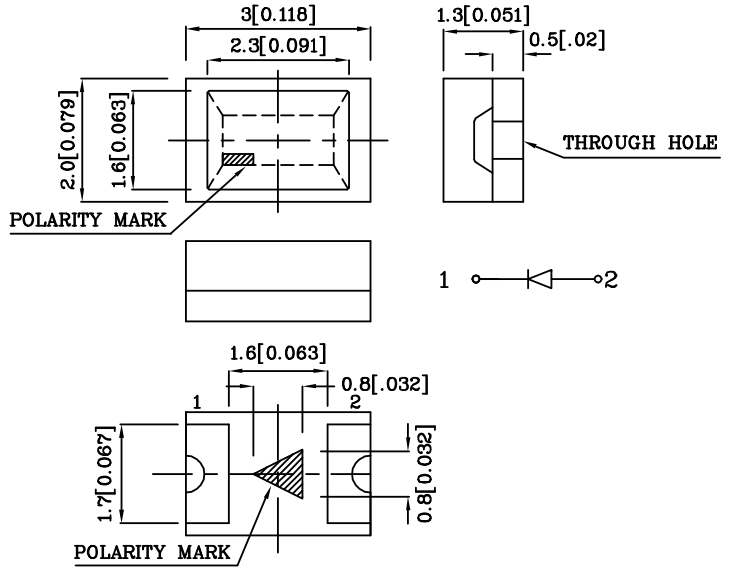


Features

- 3.0mmx2.0mm SMT LED,1.3mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- RoHS COMPLIANT.



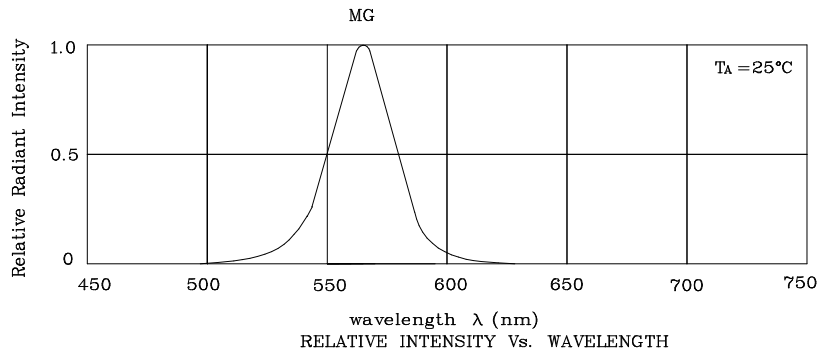
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.0079")$ unless otherwise noted.

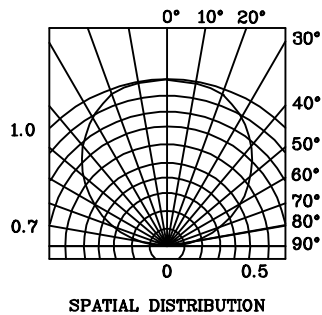
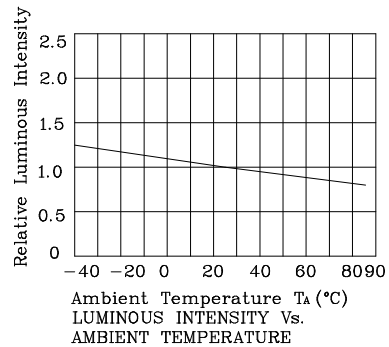
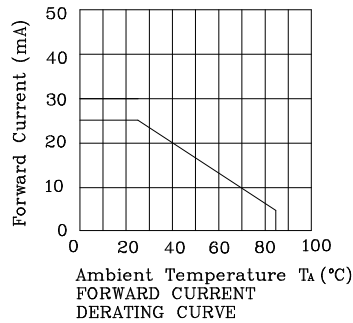
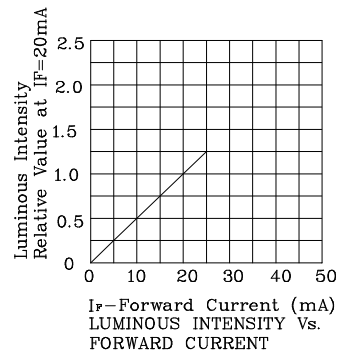
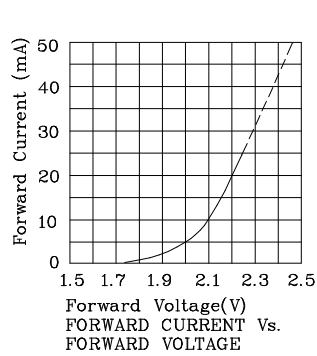
Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	IFS	140	mA
Power Dissipation	PT	105	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λP	565	nm
Wavelength of Dominant Emission (IF=20mA)	λD	568	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	$\Delta\lambda$	30	nm
Capacitance (VF=0V, f=1MHz)	C	15	pF

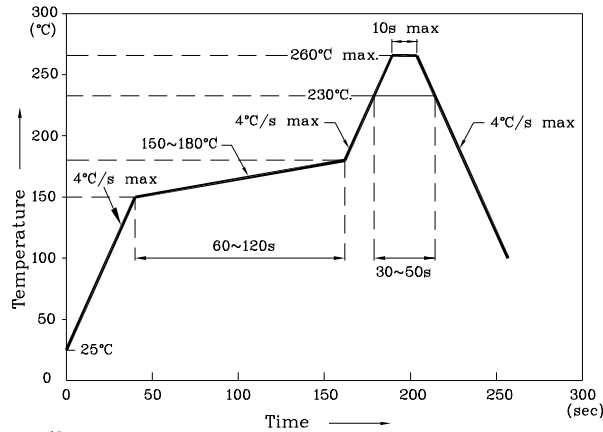
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) med		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XZMG50W-1	Green	GaP	Water Clear	7	29	565	120°



❖ MG



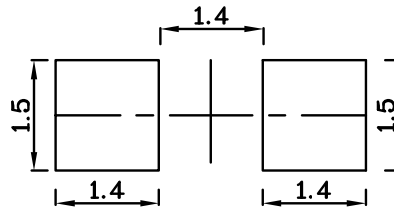
Reflow Soldering Profile For Lead-free SMT Process.



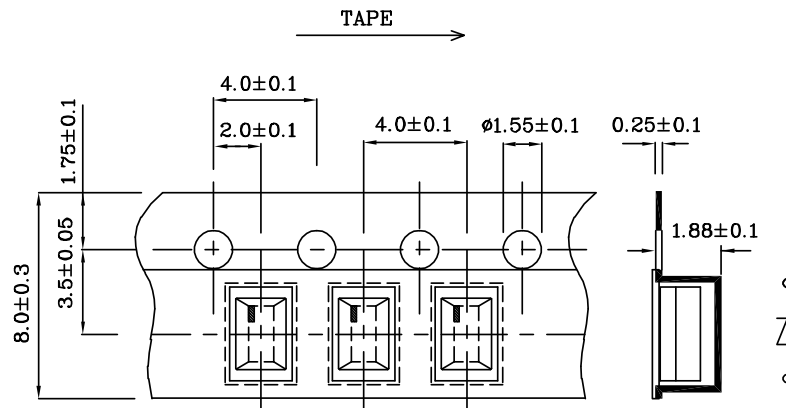
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.